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Details

Product Status	Not For New Designs
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, EBI/EMI, SCI, SPI
Peripherals	POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	52-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12c32cpbe25

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



- Operating frequency:
 - 32MHz equivalent to 16MHz bus speed for single chip
 - 32MHz equivalent to 16MHz bus speed in expanded bus modes
 - Option of 9S12C Family: 50MHz equivalent to 25MHz bus speed
 - All 9S12GC Family members allow a 50MHz operating frequency.
- Internal 2.5V regulator:
 - Supports an input voltage range from 2.97V to 5.5V
 - Low power mode capability
 - Includes low voltage reset (LVR) circuitry
 - Includes low voltage interrupt (LVI) circuitry
- 48-pin LQFP, 52-pin LQFP, or 80-pin QFP package:
 - Up to 58 I/O lines with 5V input and drive capability (80-pin package)
 - Up to 2 dedicated 5V input only lines (IRQ, XIRQ)
 - 5V 8 A/D converter inputs and 5V I/O
- Development support:
 - Single-wire background debugTM mode (BDM)
 - On-chip hardware breakpoints
 - Enhanced DBG12 debug features

1.1.2 Modes of Operation

User modes (expanded modes are only available in the 80-pin package version).

- Normal and emulation operating modes:
 - Normal single-chip mode
 - Normal expanded wide mode
 - Normal expanded narrow mode
 - Emulation expanded wide mode
 - Emulation expanded narrow mode
- Special operating modes:
 - Special single-chip mode with active background debug mode
 - Special test mode (Freescale use only)
 - Special peripheral mode (Freescale use only)
- Low power modes:
 - Stop mode
 - Pseudo stop mode
 - Wait mode



1.6.2 Resets

Resets are a subset of the interrupts featured in Table 1-9. The different sources capable of generating a system reset are summarized in Table 1-10. When a reset occurs, MCU registers and control bits are changed to known start-up states. Refer to the respective module Block User Guides for register reset states.

1.6.2.1 Reset Summary Table

Priority	Source	Vector
1	CRG module	0xFFFE, 0xFFFF
1	RESET pin	0xFFFE, 0xFFFF
1	VREG module	0xFFFE, 0xFFFF
2	CRG module	0xFFFC, 0xFFFD
3	CRG module	0xFFFA, 0xFFFB
	Priority 1 1 1 2 3	PrioritySource1CRG module1RESET pin1VREG module2CRG module3CRG module

Table 1-10. Reset Summary

1.6.2.2 Effects of Reset

When a reset occurs, MCU registers and control bits are changed to known start-up states. Refer to the respective module Block User Guides for register reset states. Refer to the HCS12 Multiplexed External Bus Interface (MEBI) Block Guide for mode dependent pin configuration of port A, B and E out of reset.

Refer to the PIM Block User Guide for reset configurations of all peripheral module ports.

Refer to Figure 1-2 to Figure 1-6 footnotes for locations of the memories depending on the operating mode after reset.

The RAM array is not automatically initialized out of reset.

NOTE

For devices assembled in 48-pin or 52-pin LQFP packages all non-bonded out pins should be configured as outputs after reset in order to avoid current drawn from floating inputs. Refer to Table 1-5 for affected pins.

1.7 Device Specific Information and Module Dependencies

1.7.1 **PPAGE**

External paging is not supported on these devices. In order to access the 16K flash blocks in the address range 0x8000–0xBFFF the PPAGE register must be loaded with the corresponding value for this range. Refer to Table 1-11 for device specific page mapping.

For all devices Flash Page 3F is visible in the 0xC000–0xFFFF range if ROMON is set. For all devices (except MC9S12GC16) Page 3E is also visible in the 0x4000–0x7FFF range if ROMHM is cleared and ROMON is set. For all devices apart from MC9S12C32 Flash Page 3D is visible in the 0x0000–0x3FFF range if ROMON is set...



Chapter 2 Port Integration Module (PIM9C32) Block Description

2.3.2.1.2 Port T Input Register (PTIT)

Module Base + 0x0001



Figure 2-4. Port T Input Register (PTIT)

Read: Anytime.

Write: Never, writes to this register have no effect.

Table	2-4.	PTIT	Field	Descriptions
-------	------	------	-------	--------------

Field	Description
7–0 PTIT[7:0]	Port T Input Register — This register always reads back the status of the associated pins. This can also be used to detect overload or short circuit conditions on output pins.

2.3.2.1.3 Port T Data Direction Register (DDRT)

Module Base + 0x0002



Figure 2-5. Port T Data Direction Register (DDRT)

Read: Anytime.

Write: Anytime.

Table 2-5. DDRT Field Descriptions

Field	Description
7–0	Data Direction Port T — This register configures each port T pin as either input or output.
DDRT[7:0]	The standard TIM / PWM modules forces the I/O state to be an output for each standard TIM / PWM module port associated with an enabled output compare. In these cases the data direction bits will not change.
	The DDRT bits revert to controlling the I/O direction of a pin when the associated timer output compare is disabled.
	 The timer input capture always monitors the state of the pin. Associated pin is configured as input. Associated pin is configured as output. Note: Due to internal synchronization circuits, it can take up to 2 bus cycles until the correct value is read on PTT or PTIT registers, when changing the DDRT register.



2.3.2.2.4 Port S Reduced Drive Register (RDRS)



Figure 2-13. Port S Reduced Drive Register (RDRS)

Read: Anytime.

Module Base + 0x000B

Write: Anytime.

Table 2-1	2. RDRS	Field De	scriptions
-----------	---------	-----------------	------------

Field	Description
3–0 RDRS[3:0]	 Reduced Drive Port S — This register configures the drive strength of each port S output pin as either full or reduced. If the port is used as input this bit is ignored. 0 Full drive strength at output. 1 Associated pin drives at about 1/3 of the full drive strength.

2.3.2.2.5 Port S Pull Device Enable Register (PERS)

Module Base + 0x000C



Figure 2-14. Port S Pull Device Enable Register (PERS)

Read: Anytime.

Write: Anytime.

Table 2-13. PERS Field Descriptions

Field	Description
3–0 PERS[3:0]	 Reduced Drive Port S — This register configures whether a pull-up or a pull-down device is activated, if the port is used as input or as output in wired-or (open drain) mode. This bit has no effect if the port is used as push-pull output. Out of reset a pull-up device is enabled. Pull-up or pull-down device is disabled. Either a pull-up or pull-down device is enabled.



Chapter 3 Module Mapping Control (MMCV4) Block Description

3.3.2.1 Initialization of Internal RAM Position Register (INITRM)

Module Base + 0x0010

Starting address location affected by INITRG register setting.



Figure 3-3. Initialization of Internal RAM Position Register (INITRM)

Read: Anytime

Write: Once in normal and emulation modes, anytime in special modes

NOTE

Writes to this register take one cycle to go into effect.

This register initializes the position of the internal RAM within the on-chip system memory map.

Table 3-2. INITRM Field Descriptions

Field	Description
7:3 RAM[15:11]	Internal RAM Map Position — These bits determine the upper five bits of the base address for the system's internal RAM array.
0 RAMHAL	 RAM High-Align — RAMHAL specifies the alignment of the internal RAM array. 0 Aligns the RAM to the lowest address (0x0000) of the mappable space 1 Aligns the RAM to the higher address (0xFFFF) of the mappable space



4.3.2.15 Port K Data Register (PORTK)

Module Base + 0x0032

Starting address location affected by INITRG register setting.



Figure 4-19. Port K Data Register (PORTK)

Read: Anytime

Write: Anytime

This port is associated with the internal memory expansion emulation pins. When the port is not enabled to emulate the internal memory expansion, the port pins are used as general-purpose I/O. When port K is operating as a general-purpose I/O port, DDRK determines the primary direction for each port K pin. A 1 causes the associated port pin to be an output and a 0 causes the associated pin to be a high-impedance input. The value in a DDR bit also affects the source of data for reads of the corresponding PORTK register. If the DDR bit is 0 (input) the buffered pin input is read. If the DDR bit is 1 (output) the output of the port data register is read.

This register is not in the map in peripheral or expanded modes while the EMK control bit in MODE register is set. Therefore, these accesses will be echoed externally.

When inputs, these pins can be selected to be high impedance or pulled up, based upon the state of the PUPKE bit in the PUCR register.

Field	Description		
7 Port K, Bit 7	Port K, Bit 7 — This bit is used as an emulation chip select signal for the emulation of the internal memory expansion, or as general-purpose I/O, depending upon the state of the EMK bit in the MODE register. While this bit is used as a chip select, the external bit will return to its de-asserted state (V_{DD}) for approximately 1/4 cycle just after the negative edge of ECLK, unless the external access is stretched and ECLK is free-running (ESTR bit in EBICTL = 0). See the MMC block description chapter for additional details on when this signal will be active.		
6 Port K, Bit 6	Port K, Bit 6 — This bit is used as an external chip select signal for most external accesses that are not selected by $\overline{\text{ECS}}$ (see the MMC block description chapter for more details), depending upon the state the of the EMK bit in the MODE register. While this bit is used as a chip select, the external pin will return to its deasserted state (V _{DD}) for approximately 1/4 cycle just after the negative edge of ECLK, unless the external access is stretched and ECLK is free-running (ESTR bit in EBICTL = 0).		
5:0 Port K, Bits 5:0	Port K, Bits 5:0 — These six bits are used to determine which FLASH/ROM or external memory array page is being accessed. They can be viewed as expanded addresses XAB19–XAB14 of the 20-bit address used to access up to1M byte internal FLASH/ROM or external memory array. Alternatively, these bits can be used for general-purpose I/O depending upon the state of the EMK bit in the MODE register.		

Table 4-13. PORTK Field Descriptions



Chapter 5 Interrupt (INTV1) Block Description

5.1 Introduction

This section describes the functionality of the interrupt (INT) sub-block of the S12 core platform. A block diagram of the interrupt sub-block is shown in Figure 5-1.



Figure 5-1. INTV1 Block Diagram



Field	Description
1 ASCIE	 ATD Sequence Complete Interrupt Enable 0 ATD Sequence Complete interrupt requests are disabled. 1 ATD Interrupt will be requested whenever ASCIF = 1 is set.
0 ASCIF	ATD Sequence Complete Interrupt Flag — If ASCIE = 1 the ASCIF flag equals the SCF flag (see Section 8.3.2.7, "ATD Status Register 0 (ATDSTAT0)"), else ASCIF reads zero. Writes have no effect. 0 No ATD interrupt occurred 1 ATD sequence complete interrupt pending

Table 8-1. ATDCTL2 Field Descriptions (continued)

Table 8-2. External Trigger Configurations

ETRIGLE	ETRIGP	External Trigger Sensitivity
0	0	Falling edge
0	1	Rising edge
1	0	Low level
1	1	High level

8.3.2.4 ATD Control Register 3 (ATDCTL3)

This register controls the conversion sequence length, FIFO for results registers and behavior in Freeze Mode. Writes to this register will abort current conversion sequence but will not start a new sequence.

Module Base + 0x0003



Figure 8-6. ATD Control Register 3 (ATDCTL3)

Read: Anytime

Write: Anytime

Table 8-3. ATDCTL3 Field Descriptions

Field	Description
6–3	Conversion Sequence Length — These bits control the number of conversions per sequence. Table 8-4 shows
S8C, S4C,	all combinations. At reset, S4C is set to 1 (sequence length is 4). This is to maintain software continuity to HC12
S2C, S1C	Family.



Chapter 8 Analog-to-Digital Converter (ATD10B8C) Block Description

8.3.2.9 ATD Test Register 1 (ATDTEST1)

This register contains the SC bit used to enable special channel conversions.

Module Base + 0x0009



Figure 8-11. ATD Test Register 1 (ATDTEST1)

Read: Anytime, returns unpredictable values for Bit 7 and Bit 6

Write: Anytime

Table 8-14. ATDTEST1 Field Descriptions

Field	Description
0	Special Channel Conversion Bit — If this bit is set, then special channel conversion can be selected using CC,
SC	CB, and CA of ATDCTL5. Table 8-15 lists the coding.
	0 Special channel conversions disabled
	1 Special channel conversions enabled
	Note: Always write remaining bits of ATDTEST1 (Bit7 to Bit1) zero when writing SC bit. Not doing so might result
	in unpredictable ATD behavior.

Table 8-15. Special Channel Select Coding

SC	СС	СВ	СА	Analog Input Channel
1	0	Х	Х	Reserved
1	1	0	0	V _{RH}
1	1	0	1	V _{RL}
1	1	1	0	(V _{RH} +V _{RL}) / 2
1	1	1	1	Reserved



10.3.3.3 Data Length Register (DLR)

This register keeps the data length field of the CAN frame.

Module Base + 0x00XB



Table 10-31. DLR Register Field Descriptions

Field	Description
3:0 DLC[3:0]	Data Length Code Bits — The data length code contains the number of bytes (data byte count) of the respective message. During the transmission of a remote frame, the data length code is transmitted as programmed while the number of transmitted data bytes is always 0. The data byte count ranges from 0 to 8 for a data frame. Table 10-32 shows the effect of setting the DLC bits.

Table 10-32. Data Length Codes

	Data Byte					
DLC3	DLC2	DLC1	DLC0	Count		
0	0	0	0	0		
0	0	0	1	1		
0	0	1	0	2		
0	0	1	1	3		
0	1	0	0	4		
0	1	0	1	5		
0	1	1	0	6		
0	1	1	1	7		
1	0	0	0	8		

10.3.3.4 Transmit Buffer Priority Register (TBPR)

This register defines the local priority of the associated message buffer. The local priority is used for the internal prioritization process of the MSCAN and is defined to be highest for the smallest binary number. The MSCAN implements the following internal prioritization mechanisms:

- All transmission buffers with a cleared TXEx flag participate in the prioritization immediately before the SOF (start of frame) is sent.
- The transmission buffer with the lowest local priority field wins the prioritization.



Chapter 13 Serial Communications Interface (S12SCIV2) Block Description

SCI Status Register 2 (SCISR2) 13.3.2.5



Figure 13-7. SCI Status Register 2 (SCISR2)

Read: Anytime

Write: Anytime; writing accesses SCI status register 2; writing to any bits except TXDIR and BRK13 (SCISR2[1] & [2]) has no effect

Table	13-6.	SCISR2	Field	Descri	ptions
-------	-------	--------	-------	--------	--------

Field	Description
2 BK13	 Break Transmit Character Length — This bit determines whether the transmit break character is 10 or 11 bit respectively 13 or 14 bits long. The detection of a framing error is not affected by this bit. 0 Break Character is 10 or 11 bit long 1 Break character is 13 or 14 bit long
1 TXDIR	 Transmitter Pin Data Direction in Single-Wire Mode. — This bit determines whether the TXD pin is going to be used as an input or output, in the Single-Wire mode of operation. This bit is only relevant in the Single-Wire mode of operation. 0 TXD pin to be used as an input in Single-Wire mode 1 TXD pin to be used as an output in Single-Wire mode
0 RAF	 Receiver Active Flag — RAF is set when the receiver detects a logic 0 during the RT1 time period of the start bit search. RAF is cleared when the receiver detects an idle character. 0 No reception in progress 1 Reception in progress

0

0



Chapter 15 Timer Module (TIM16B8CV1) Block Description

Version Number	Revision Dates	Effective Date	Author	Description of Changes	
01.03	06 Feb 2006	06 Feb 2006	S. Chinnam	am Corrected the type at 0x006 and later in the documen from TSCR2 and TSCR1	
01.04	08 July 2008	08 July 2008	S. Chinnam	Revised flag clearing procedure, whereby TEN bit must be set when clearing flags.	
01.05	05 May 2010	05 May 2010	Ame Wang	-in 15.3.2.8/15-446,add Table 15-11 -in 15.3.2.11/15-450,TCRE bit description part,add Note -in 15.4.3/15-459,add Figure 15-29	

Table 15-1. Revision History

15.1 Introduction

The basic timer consists of a 16-bit, software-programmable counter driven by a seven-stage programmable prescaler.

This timer can be used for many purposes, including input waveform measurements while simultaneously generating an output waveform. Pulse widths can vary from microseconds to many seconds.

This timer contains 8 complete input capture/output compare channels and one pulse accumulator. The input capture function is used to detect a selected transition edge and record the time. The output compare function is used for generating output signals or for timer software delays. The 16-bit pulse accumulator is used to operate as a simple event counter or a gated time accumulator. The pulse accumulator shares timer channel 7 when in event mode.

A full access for the counter registers or the input capture/output compare registers should take place in one clock cycle. Accessing high byte and low byte separately for all of these registers may not yield the same result as accessing them in one word.

15.1.1 Features

The TIM16B8CV1 includes these distinctive features:

- Eight input capture/output compare channels.
- Clock prescaling.
- 16-bit counter.
- 16-bit pulse accumulator.



15.3.2.14 Timer Input Capture/Output Compare Registers High and Low 0–7 (TCxH and TCxL)



Figure 15-23. Timer Input Capture/Output Compare Register x Low (TCxL)

Depending on the TIOS bit for the corresponding channel, these registers are used to latch the value of the free-running counter when a defined transition is sensed by the corresponding input capture edge detector or to trigger an output action for output compare.

Read: Anytime

Write: Anytime for output compare function.Writes to these registers have no meaning or effect during input capture. All timer input capture/output compare registers are reset to 0x0000.

NOTE

Read/Write access in byte mode for high byte should takes place before low byte otherwise it will give a different result.



FPOPEN	FPHDIS	FPHS[1]	FPHS[0]	FPLDIS	FPLS[1]	FPLS[0]	Function ⁽¹⁾
1	1	х	х	1	х	х	No protection
1	1	х	х	0	х	х	Protect low range
1	0	х	х	1	х	х	Protect high range
1	0	х	х	0	х	х	Protect high and low ranges
0	1	х	х	1	х	х	Full Flash array protected
0	0	х	х	1	х	х	Unprotected high range
0	1	х	х	0	х	х	Unprotected low range
0	0	х	х	0	х	х	Unprotected high and low ranges

Table 18-9. Flash Protection Function

1. For range sizes refer to Table 18-10 and or Table 18-11.

Table 18-10	. Flash I	Protection	Higher	Address	Range
-------------	-----------	------------	--------	---------	-------

FPHS[1:0]	Address Range	Range Size
00	0xF800-0xFFFF	2 Kbytes
01	0xF000-0xFFFF	4 Kbytes
10	0xE000-0xFFFF	8 Kbytes
11	0xC000-0xFFFF	16 Kbytes

Table 18-11. Flash Protection Lower Address Range

FPLS[1:0]	Address Range	Range Size
00	0x4000–0x41FF	512 bytes
01	0x4000-0x43FF	1 Kbyte
10	0x4000-0x47FF	2 Kbytes
11	0x4000-0x4FFF	4 Kbytes

Figure 18-9 illustrates all possible protection scenarios. Although the protection scheme is loaded from the Flash array after reset, it is allowed to change in normal modes. This protection scheme can be used by applications requiring re-programming in single chip mode while providing as much protection as possible if no re-programming is required.



Chapter 19 64 Kbyte Flash Module (S12FTS64KV4)



Note: 0x38–0x3F correspond to the PPAGE register content

Figure 19-3. Flash Memory Map



Chapter 20 96 Kbyte Flash Module (S12FTS96KV1)

20.1.3 Modes of Operation

See Section 20.4.2, "Operating Modes" for a description of the Flash module operating modes. For program and erase operations, refer to Section 20.4.1, "Flash Command Operations".

20.1.4 Block Diagram

Figure 20-1Figure 20-2 shows a block diagram of the FTS128K1FTS96K module.





NP_

Chapter 21 128 Kbyte Flash Module (S12FTS128K1V1)



Note: 0x38–0x3F correspond to the PPAGE register content

Figure 21-2. Flash Memory Map



21.4.1.4 Illegal Flash Operations

21.4.1.4.1 Access Error

The ACCERR flag in the FSTAT register will be set during the command write sequence if any of the following illegal Flash operations are performed causing the command write sequence to immediately abort:

- 1. Writing to the Flash address space before initializing the FCLKDIV register
- 2. Writing a misaligned word or a byte to the valid Flash address space
- 3. Writing to the Flash address space while CBEIF is not set
- 4. Writing a second word to the Flash address space before executing a program or erase command on the previously written word
- 5. Writing to any Flash register other than FCMD after writing a word to the Flash address space
- 6. Writing a second command to the FCMD register before executing the previously written command
- 7. Writing an invalid command to the FCMD register
- 8. Writing to any Flash register other than FSTAT (to clear CBEIF) after writing to the FCMD register
- 9. The part enters stop mode and a program or erase command is in progress. The command is aborted and any pending command is killed
- 10. When security is enabled, a command other than mass erase originating from a non-secure memory or from the background debug mode is written to the FCMD register
- 11. A 0 is written to the CBEIF bit in the FSTAT register to abort a command write sequence.

The ACCERR flag will not be set if any Flash register is read during the command write sequence. If the Flash array is read during execution of an algorithm (CCIF=0), the Flash module will return invalid data and the ACCERR flag will not be set. If an ACCERR flag is set in the FSTAT register, the Flash command controller is locked. It is not possible to launch another command until the ACCERR flag is cleared.

21.4.1.4.2 Protection Violation

The PVIOL flag in the FSTAT register will be set during the command write sequence after the word write to the Flash address space if any of the following illegal Flash operations are performed, causing the command write sequence to immediately abort:

- 1. Writing a Flash address to program in a protected area of the Flash array (see Section 21.3.2.5).
- 2. Writing a Flash address to erase in a protected area of the Flash array.
- 3. Writing the mass erase command to the FCMD register while any protection is enabled.

If the PVIOL flag is set, the Flash command controller is locked. It is not possible to launch another command until the PVIOL flag is cleared.



C.1.2 52-Pin LQFP Package







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SECTION AB-AB ROTATED 90 ° CLOCKWISE

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER DATUM PLANE-H-IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

2. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-

PLANE -H-DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 (0.018). MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).



	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	10.00 BSC		0.394 BSC		
A1	5.00 BSC		0.197 BSC		
В	10.00 BSC		0.394 BSC		
B1	5.00 BSC		0.197 BSC		
С		1.70		0.067	
C1	0.05	0.20	0.002	0.008	
C2	1.30	1.50	0.051	0.059	
D	0.20	0.40	0.008	0.016	
E	0.45	0.75	0.018	0.030	
F	0.22	0.35	0.009	0.014	
G	0.65 BSC		0.026 BSC		
J	0.07	0.20	0.003	0.008	
K	0.50 REF		0.020 REF		
R1	0.08	0.20	0.003	0.008	
S	12.00 BSC		0.472 BSC		
S1	6.00 BSC		0.236 BSC		
U	0.09	0.16	0.004	0.006	
V	12.00 BSC		0.472 BSC		
V1	6.00 BSC		0.236 BSC		
W	0.20 REF		0.008 REF		
Z	1.00 REF		0.039 REF		
θ	0°	7°	0°	7°	
θ1	0°		0°		
θ2	12° REF		12° REF		
θ3	12° REF		12° REF		

Figure C-2. 52-Pin LQFP Mechanical Dimensions (Case no. 848D-03)



Appendix D Derivative Differences

The Device User Guide provides information about the MC9S12C-Family and the MC9S12GC-Family. The C-Family and the GC-Family offer an extensive range of package, temperature and speed options. The members of the GC-Family are a subset of the C-family that do not feature a CAN module.

Table D-1. shows a feature overview of the C and GC family members.

Flash	RAM	Device	CAN	SCI	SPI	A/D	PWM	Timer
128K	4K	MC9S12C128	1	1	1	8ch	6ch	8ch
		MC9S12GC128		1	1	8ch	6ch	8ch
96K	4K	MC9S12C96	1	1	1	8ch	6ch	8ch
		MC9S12GC96	_	1	1	8ch	6ch	8ch
64K	4K	MC9S12C64	1	1	1	8ch	6ch	8ch
		MC9S12GC64		1	1	8ch	6ch	8ch
32K	2K	MC9S12C32	1	1	1	8ch	6ch	8ch
		MC9S12GC32	_	1	1	8ch	6ch	8ch
16K	1K	MC9S12GC16		1	1	8ch	6ch	8ch

Table D-1. List of MC9S12C and MC9S12GC Family	v members ⁽¹⁾

1. All family memebers are available in 80QFP, 52LQFP and 48LQFP package options